

# Material Set Change:

Package Material Set		Carsem	ASE Chungli
8L, and 14L SOICN	Die Attach	Ablestik 84-1 LMISR4	Hitachi EN4900
	Mold Compound	Sumitomo 6600H	Hitachi CEL9240HF10AK
	Wire	0.8mil, 1.0mil, 1.2 and 1.3 mil Gold wire	0.8mil, 1.0mil, 1.2 and 1.3 mil Gold wire

## QUALIFICATION RESULT SUMMARY SOICn package at ASE Chungli (AET)

	STRESS TESTS and CONDITIONS					
	Highly Accelerated Stress Test (HAST)*	Temperature Cycle (TC)*	Autoclave (AC)*	Solder Heat Resistance (SHR)*	High Temperature Storage (HTS)	Field Induced Charged Device Model (FICDM)
	JEDEC JESD22-A110	JEDEC JESD22-A104	JEDEC JESD22-A102	ADI-0049	JEDEC JESD22-A103	JEDEC JESD22-C101
Qual Vehicle 1	PASS	PASS	PASS	PASS	PASS	PASS ±1250V
Qual Vehicle 2	PASS	PASS	PASS	PASS	PASS	PASS ±1250V
<b>TOTAL:</b>	<b>0 / 462</b>	<b>0 / 462</b>	<b>0 / 462</b>	<b>0 / 66</b>	<b>0 / 149</b>	<b>-</b>

\*These samples were subjected to preconditioning (per J-STD-020 Level 1) prior to the start of the stress test. Level 1 preconditioning consists of the following: Bake: 24 hrs @ 125°C, Soak: Unbiased Soak: 168 hrs @ 85°C, 85%RH, Reflow: 3 passes through an oven with a peak temperature of 260°C.